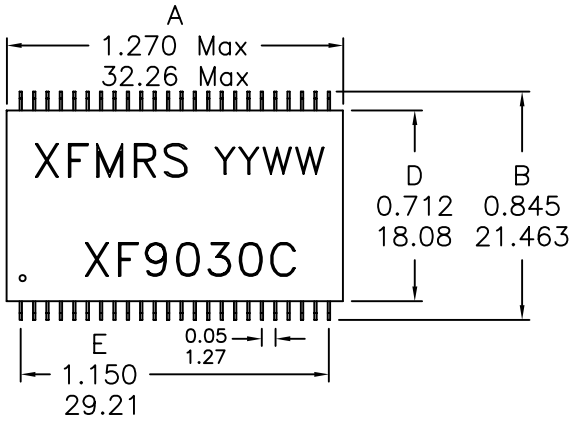
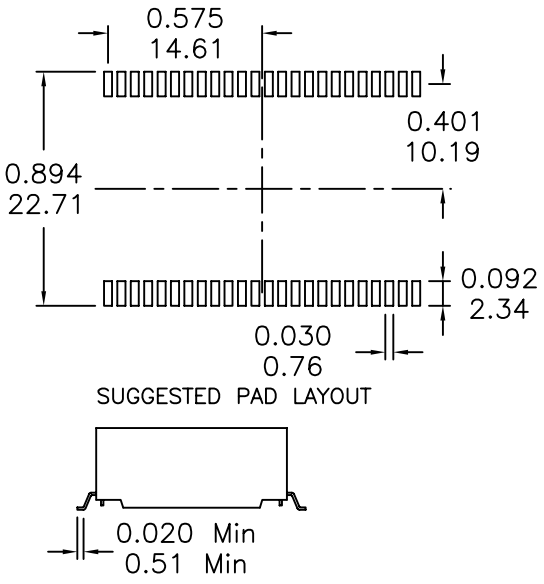
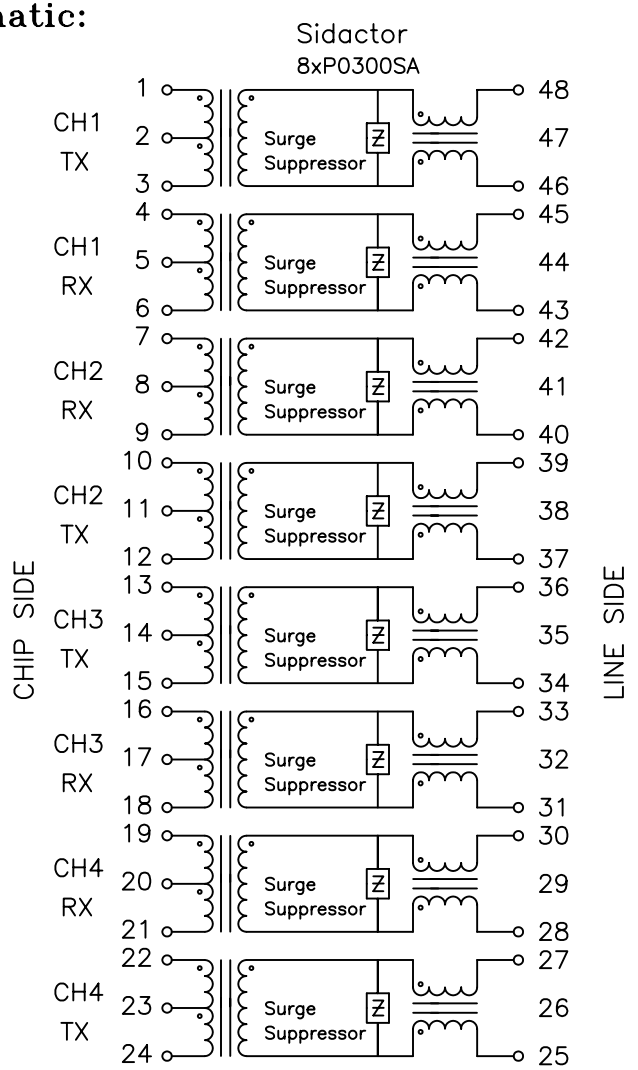
1. Mechanical Dimensions:





2. Schematic:



3. Electrical Specifications: @25°

Turns Ratio: Chip/Line TX 1CT:2.4 RX 1CT:1

Isolation Voltage: 1500 Vrms (Input to Output),1Min

Line OCL: 1.20mH Minimum @10KHz,100mV, 25°C

0.60mH Minimum @10KHz,100mV, −40°C

Line Q: 8 Minimum @10KHz,50mV

Tx Chip Leakage Inductance: 0.5uH Maximum @100KHz 100mV Line Shorted

Rx Chip Leakage Inductance: 0.8uH Maximum @100KHz 100mV Line Shorted

Chip/Line Cw/w: 35pF Max @100KHz 100mV

Chip DCR: 0.80 Ohms Max

TX Line DCR: 1.5 Ohms Max

Rx Line DCR: 1.10 Ohms Max

Notes:

1. Solderability: Leads shall meet MIL−STD−202G, Method 208H for solderability.
2. Flammability: UL94V−0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from −40°C to +85°C
6. Storage Temperature Range: −55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS 5/6 Compliant,63/37 leaded solder dipping on FG pins
11. Recommended IR Reflow temp 225C Max.

DOC. REV: A/2

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XFMRS INC. www.XFMRS.com	Title: T1/CEPT/ISDN−PRI TRANSFORMER		
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Inch Dimensions in Inch/mm	P/N: XF9030C		REV. A
	DWN.	Mei Chen	Jun−03−10
	CHK.	YK Liao	Jun−03−10
SHT 1 OF 1	APP.	BW	Jun−03−10